



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B102KC8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1nF, 100V, ±10%, X7R, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>102</u> <u>K</u> <u>C</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

| 1 | Series | Samsung Multi-layer Ceramic Capacitor | | | | | | | | |
|-----|---------------|---------------------------------------|-----------|----|-----|---------|-----------|----|---------------|--------------|
| 2 | Size | 0603 (ir | nch code) | L: | 1.6 | ± 0.1 | mm | W: | 0.8 ± 0.1 | mm |
| | | | | | | | | | | |
| 3 | Dielectric | X7R | | | 8 | Inner e | electrode | N | li | |
| 4 | Capacitance | 1 nF | - | | | Termir | nation | C | Cu | |
| (5) | Capacitance | ±10 % | | | | Plating | j | S | n 100% | (Pb Free) |
| | tolerance | | | | 9 | Produc | ct | N | Iormal | |
| 6 | Rated Voltage | 100 V | | | 10 | Specia | ıl | R | Reserved for | future use |
| 7 | Thickness | 0.8 ± | 0.1 mm | | 11) | Packa | ging | C | ardboard T | ype, 7" reel |

B. Samsung Reliablility Test and Judgement condition

| | Performance | Test condition | | | | | |
|-------------------|--|---------------------------------------|--|--|--|--|--|
| Capacitance | Within specified tolerance | 1klb±10% 1.0±0.2Vrms | | | | | |
| Tan δ (DF) | 0.025 max. | | | | | | |
| Insulation | 10,000Mohm or 500Mohm⋅ <i>μ</i> F | Rated Voltage 60~120 sec. | | | | | |
| Resistance | Whichever is Smaller | | | | | | |
| Appearance | No abnormal exterior appearance | Microscope (×10) | | | | | |
| Withstanding | No dielectric breakdown or | 200% of the rated voltage | | | | | |
| Voltage | mechanical breakdown | | | | | | |
| Temperature | X7R | | | | | | |
| Characterisitcs | (From -55℃ to 125℃, Capacitance change shoud be within ±15%) | | | | | | |
| Adhesive Strength | No peeling shall be occur on the | 500g·F, for 10±1 sec. | | | | | |
| of Termination | terminal electrode | | | | | | |
| Bending Strength | Capacitance change : within ±12.5% | Bending to the limit (1mm) | | | | | |
| | | with 1.0mm/sec. | | | | | |
| Solderability | More than 75% of terminal surface | SnAg3.0Cu0.5 solder | | | | | |
| | is to be soldered newly | 245±5℃, 3±0.3sec. | | | | | |
| | | (preheating : 80~120 ℃ for 10~30sec.) | | | | | |
| | | | | | | | |
| Resistance to | Capacitance change: within ±7.5% | Solder pot : 270±5℃, 10±1sec. | | | | | |
| Soldering heat | Tan δ, IR : initial spec. | | | | | | |

| | Performance | Test condition |
|------------------|------------------------------------|-------------------------------------|
| Vibration Test | Capacitance change : within ±5% | Amplitude : 1.5mm |
| | Tan δ, IR : initial spec. | From 10Hz to 55Hz (return : 1min.) |
| | | 2hours × 3 direction (x, y, z) |
| Moisture | Capacitance change : within ±12.5% | With rated voltage |
| Resistance | Tan δ : 0.05 max | 40±2℃, 90~95%RH, 500+12/-0hrs |
| | IR: 500Mohm or 25Mohm · μF | |
| | Whichever is Smaller | |
| High Temperature | Capacitance change : within ±12.5% | With 200% of the rated voltage |
| Resistance | Tan δ : 0.05 max | Max. operating temperature |
| | IR: 1000Mohm or 50Mohm · μF | |
| | Whichever is Smaller | 1000+48/-0hrs |
| Temperature | Capacitance change : within ±7.5% | 1 cycle condition |
| Cycling | Tan δ, IR : initial spec. | Min. operating temperature → 25°C |
| | | → Max. operating temperature → 25°C |
| | | |
| | | 5 cycle test |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\text{C}$, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.